

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10687759			
<b>Filing Date:</b>	20-Oct-2003			
<b>Title of Invention:</b>	Multi-layered complementary wire structure and manufacturing method thereof			
<b>First Named Inventor:</b>	Yu-Cheng Chen			
<b>Filer:</b>	Clark A. Jablon/Rose Valdez			
<b>Attorney Docket Number:</b>	4006-270			
Filed as Large Entity				
<b>Utility Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 3 months with \$0 paid	1253	1	1020	1020

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1020</b>